IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 3 and 6-8 have been amended and claims 9-20 have been added as follows:

Listing of Claims:

Claim 1 (original): A laminated ceramic substrate formed by laminating ceramic layers each having a circuit element pattern formed on a surface thereof, the laminated ceramic substrate comprising a side electrode in which a side edge electrode layer formed on a side edge portion of the ceramic layer overlaps with and connects to a side edge electrode layer formed on a side edge portion of another ceramic layer directly above and/or directly below the former ceramic layer, the side edge electrode layer comprising a parallel wall unexposed and approximately parallel to a side surface of the laminated ceramic substrate and a perpendicular wall approximately perpendicular to the side surface of the laminated ceramic substrate, a length La of the parallel wall and a depth Lb of the parallel wall from the side surface of the laminated ceramic substrate having a relationship of $La > Lb$.

Claim 2 (original): A laminated ceramic substrate according to claim 1, wherein the parallel wall and perpendicular wall are connected by a corner portion with an R-shape in which R is greater than 0.02 mm.

Claim 3 (currently amended): A laminated ceramic substrate according to claim 1 [[or 2]],

wherein a sum of depths of opposite side edge electrode layers partially differs with respect to a laminated direction.

Claim 4 (original): A manufacturing method for a laminated ceramic substrate formed by laminating ceramic layers each having a circuit element pattern formed on a surface thereof, the manufacturing method for the laminated ceramic substrate comprising

a step of providing a through hole for a side electrode including at least four straight-line portions in a green sheet to become a ceramic layer.

Claim 5 (original): A manufacturing method for a laminated ceramic substrate according to claim 4, wherein the through hole for a side electrode provided in at least one green sheet differs in size from a through hole for a side electrode provided in another green sheet.

Claim 6 (currently amended): A manufacturing method for a laminated ceramic substrate formed by laminating ceramic layers each having a circuit element pattern formed on a surface thereof according to claim 4 [[or 5]], the manufacturing method for the laminated ceramic substrate comprising:

a first step of preparing a plurality of green sheets to become ceramic layers and providing in a required number of the green sheets thereof a through hole for a via hole to become a circuit element pattern and a through hole for a side electrode including at least four straight-line portions;

a second step of filling the through hole for a via hole and through hole for a side electrode of the plurality of green sheets after the first step with a conductive material;

a third step of printing a circuit element pattern with the conductive material on each surface

of the plurality of green sheets after the second step;

a fourth step of laminating the green sheets after the third step and integrating the green sheets by heat press or other methods to obtain a green sheet laminated body;

a fifth step of dividing the green sheet laminated body after the fourth step to obtain a green sheet laminated body chip; and

a sixth step of firing the green sheet laminated body chip after the fifth step to obtain the laminated ceramic substrate.

Claim 7 (currently amended): A manufacturing method for a laminated ceramic substrate according to claim 4, ~~5, or 6,~~ comprising:

a fifth step of firing the green sheet laminated body after the fourth step to obtain a mother laminated ceramic substrate; and

a sixth step of dividing the mother laminated ceramic substrate after the fifth step to obtain the laminated ceramic substrate.

Claim 8 (currently amended): A manufacturing method for a laminated ceramic substrate according to claim 4, ~~5, 6, or 7,~~ wherein the second step of filling the through hole for a via hole and through hole for a side electrode with the conductive material is performed simultaneously with the third step of printing the circuit element pattern with the conductive material on each surface of the green sheets.

Claim 9 (new): A laminated ceramic substrate according to claim 2, wherein a sum of depths of opposite side edge electrode layers partially differs with respect to a laminated direction.

Claim 10 (new): A manufacturing method for a laminated ceramic substrate formed by laminating ceramic layers each having a circuit element pattern formed on a surface thereof according to claim 5, the manufacturing method for the laminated ceramic substrate comprising:

a first step of preparing a plurality of green sheets to become ceramic layers and providing in a required number of the green sheets thereof a through hole for a via hole to become a circuit element pattern and a through hole for a side electrode including at least four straight-line portions;

a second step of filling the through hole for a via hole and through hole for a side electrode of the plurality of green sheets after the first step with a conductive material;

a third step of printing a circuit element pattern with the conductive material on each surface of the plurality of green sheets after the second step;

a fourth step of laminating the green sheets after the third step and integrating the green sheets by heat press or other methods to obtain a green sheet laminated body;

a fifth step of dividing the green sheet laminated body after the fourth step to obtain a green sheet laminated body chip; and

a sixth step of firing the green sheet laminated body chip after the fifth step to obtain the laminated ceramic substrate.

Claim 11 (new): A manufacturing method for a laminated ceramic substrate according to claim 5, comprising:

a fifth step of firing the green sheet laminated body after the fourth step to obtain a mother laminated ceramic substrate; and

a sixth step of dividing the mother laminated ceramic substrate after the fifth step to obtain the laminated ceramic substrate.

Claim 12 (new): A manufacturing method for a laminated ceramic substrate according to claim 6, comprising:

a fifth step of firing the green sheet laminated body after the fourth step to obtain a mother laminated ceramic substrate; and

a sixth step of dividing the mother laminated ceramic substrate after the fifth step to obtain the laminated ceramic substrate.

Claim 13 (new): A manufacturing method for a laminated ceramic substrate according to claim 10, comprising:

a fifth step of firing the green sheet laminated body after the fourth step to obtain a mother laminated ceramic substrate; and

a sixth step of dividing the mother laminated ceramic substrate after the fifth step to obtain the laminated ceramic substrate.

Claim 14 (new): A manufacturing method for a laminated ceramic substrate according to claim 5, wherein the second step of filling the through hole for a via hole and through hole for a side electrode with the conductive material is performed simultaneously with the third step of printing the circuit element pattern with the conductive material on each surface of the green sheets.

Claim 15 (new): A manufacturing method for a laminated ceramic substrate according to claim 6, wherein the second step of filling the through hole for a via hole and through hole for a side

electrode with the conductive material is performed simultaneously with the third step of printing the circuit element pattern with the conductive material on each surface of the green sheets.

Claim 16 (new): A manufacturing method for a laminated ceramic substrate according to claim 10, wherein the second step of filling the through hole for a via hole and through hole for a side electrode with the conductive material is performed simultaneously with the third step of printing the circuit element pattern with the conductive material on each surface of the green sheets.

Claim 17 (new): A manufacturing method for a laminated ceramic substrate according to claim 7, wherein the second step of filling the through hole for a via hole and through hole for a side electrode with the conductive material is performed simultaneously with the third step of printing the circuit element pattern with the conductive material on each surface of the green sheets.

Claim 18 (new): A manufacturing method for a laminated ceramic substrate according to claim 11, wherein the second step of filling the through hole for a via hole and through hole for a side electrode with the conductive material is performed simultaneously with the third step of printing the circuit element pattern with the conductive material on each surface of the green sheets.

Claim 19 (new): A manufacturing method for a laminated ceramic substrate according to claim 12, wherein the second step of filling the through hole for a via hole and through hole for a side electrode with the conductive material is performed simultaneously with the third step of printing the circuit element pattern with the conductive material on each surface of the green sheets.

Claim 20 (new): A manufacturing method for a laminated ceramic substrate according to claim 13, wherein the second step of filling the through hole for a via hole and through hole for a

side electrode with the conductive material is performed simultaneously with the third step of printing the circuit element pattern with the conductive material on each surface of the green sheets.